

IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 15.0001

CB Certificate No.: 026/QCA

Schedule Number: IECC	Q-C BSI 15.00	01-S	Rev No.: 11	Revision Date: 20	20/12/24	Page 1 of 1
Board Types:	Rigid singl	ole-sided with le & double-s	plated throug ided with plain th through hol	holes	BS 123 BS 123	3300-003 3200-003 3100-003 3600-003
Base Materials:	Epoxide W Polyimide	oven Glass Film				
Board Size:	495.30 mm x 419.10 mm multilayer 261.87 mm x 322.33 mm multilayer					3300-003 6600-003
Number of Layers	32 maximum 10 maximum					3300-003 6600-003
Conductors	0.10 mm (photomech) Tolerance -0.02 mm +0.03 mm					
Plated-through Hole Diameter:	0.20 mm 0.80 mm	Minimum Minimum	Finished hol			3300-003 3600-003
Aspect Ratio:	16.4 : 1 2.27 : 1	Maximum Maximum				3300-003 3600-003

Finishes: * Hot Air Solder Levelling

Immersion Silver

 $2.5 \mu m$ Gold over Copper Edge Contacts Liquid Photopolymer Solder Resist

Legend; UV or Oven Cured Solder resist UV cured

Additional: Selective Electroplated Gold (2.5 μm) on Copper

Selective Electroless Gold (0.07 µm) on Nickel

* This finish meets the Solderability requirements

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